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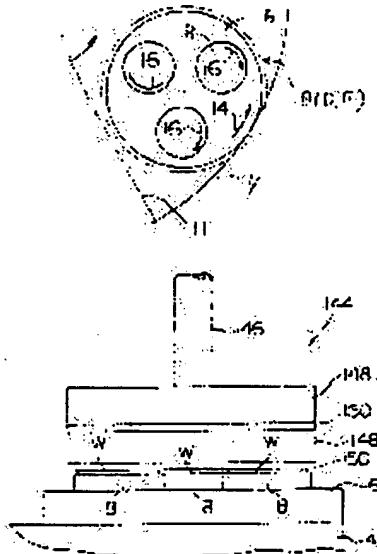
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(54) POLISHING DEVICE

(57)Abstract:

PURPOSE: To make a semiconductor wafer difference stockremoval and accuracy polishable in consecutive order, by installing more than one unit of chuck tables rotatably on plural intermediate tables free of rotation in the circumferential direction of an index table which rotates intermittently.

CONSTITUTION: Each intermediate table 6 is positioned at a polishing region B or D and F whereby polishing is carried out. That is to say, a suspension rod 146 goes down, and a disc member 148 and an abrasive pad 150 also go down whereby this pad 150 is pressed to the surface of a work W being held on each surface of a chuck table 8, and simultaneously the rod 146 is driven in rotation. Therefore, the disc member 148 and the pad 150 are rotationally driven, while abrasive slurry containing floating abrasive grains is fed to the pad 150. And, during polishing operation, each intermediate table 6 turns round toward an arrow 14, while each of chuck tables 8 is rotated toward an arrow 16 whereby a work W on the table 8 revolves and simultaneously rotates and furthermore, with intermittent rotation of an index table 4, the work is polishable at plural polishing regions.



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